3.2x1.6mm SMD CHIP LED LAMP

Description

AP3216SYCK SUPER BRIGHT YELLOW

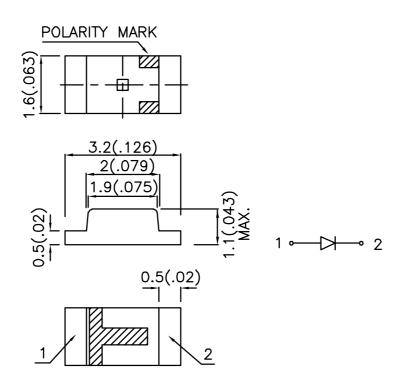
The Super Bright Yellow source color devices are made

with DH InGaAIP on GaAs substrate Light Emitting Diode.

Features

- •3.2mmx1.6mm SMT LED, 1.1mm THICKNESS.
- •LOW POWER CONSUMPTION.
- •WIDE VIEWING ANGLE.
- •IDEAL FOR BACKLIGHT AND INDICATOR.
- •VARIOUS COLORS AND LENS TYPES AVAILABLE.
- •PACKAGE : 2000PCS / REEL.
- •UV RATED EPOXY.
- •RoHS COMPLIANT.

Package Dimensions



Notes:
 All dimensions are in millimeters (inches).
 Tolerance is ±0.2(0.008") unless otherwise noted.
 Specifications are subject to change without notice.

SPEC NO: DSAA8437 APPROVED: J. Lu

REV NO: V.6 CHECKED: Allen Liu DATE: MAR/19/2005 DRAWN: W.J.ZHU

PAGE: 1 OF 4 ERP:1203000429

Selection Gui	de				
Part No.	Dice	Lens Type	lv (mcd) @ 20mA		Viewing Angle
			Min.	Тур.	2 0 1/2
AP3216SYCK	SUPER BRIGHT YELLOW (InGaAIP)	WATER CLEAR	18	120	120°

Note:

1. θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.

Electrical / Optical Characteristics at TA=25°C

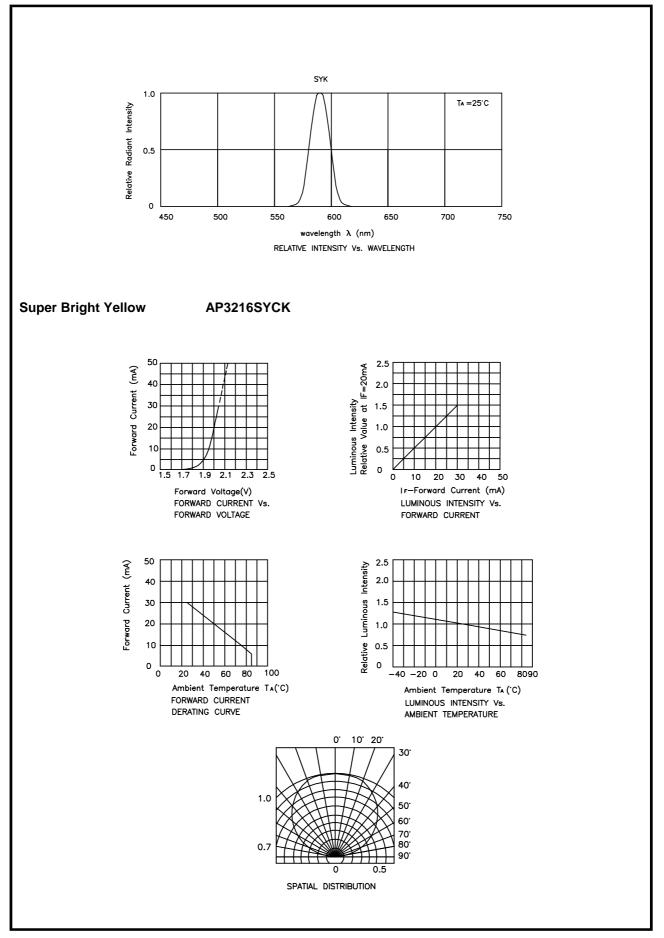
Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Super Bright Yellow	590		nm	IF=20mA
λD	Dominant Wavelength	Super Bright Yellow	590		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Super Bright Yellow	20		nm	IF=20mA
С	Capacitance	Super Bright Yellow	20		pF	VF=0V;f=1MHz
VF	Forward Voltage	Super Bright Yellow	2.0	2.5	V	IF=20mA
IR	Reverse Current	Super Bright Yellow		10	uA	VR = 5V

Absolute Maximum Ratings at TA=25°C

Parameter	Super Bright Yellow	Units
Power dissipation	125	mW
DC Forward Current	30	mA
Peak Forward Current [1]	175	mA
Reverse Voltage	5	V
Operating/Storage Temperature -40°C To +85°C		

Note:

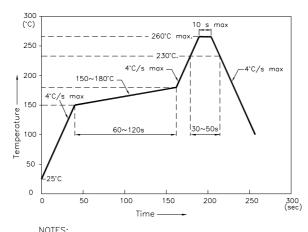
1. 1/10 Duty Cycle, 0.1ms Pulse Width.



REV NO: V.6 CHECKED: Allen Liu DATE: MAR/19/2005 DRAWN: W.J.ZHU PAGE: 3 OF 4 ERP:1203000429

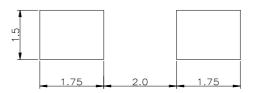


Reflow Soldering Profile For Lead-free SMT Process.

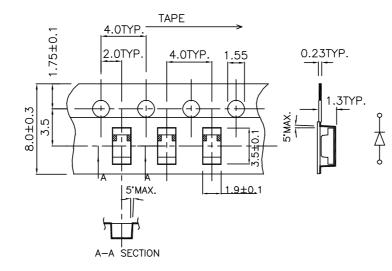


NOTES:
1.We recommend the reflow temperature 245°C(+/-5°C).The maximum soldering temperature should be limited to 260°C.
2.Don't cause stress to the epoxy resin while it is exposed to high temperature.
3.Number of reflow process shall be 2 times or less.

Recommended Soldering Pattern (Units : mm)



Tape Specifications (Units : mm)



Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity, or wavelength),

the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm

2. Luminous Intensity: +/-15%

3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

REV NO: V.6 CHECKED: Allen Liu DATE: MAR/19/2005 DRAWN: W.J.ZHU PAGE: 4 OF 4 ERP:1203000429